Amendments to the Claims:

This listing of claims will replace all prior versions and listings of claims in the application:

Listings of Claims:

1. (original) A semiconductor device having a semiconductor chip mounted over a substrate in which an interconnect is formed, by using an adhesive layer to permit contact conduction between a stud bump of the semiconductor chip and an interconnect of a tape substrate,

wherein over the stud bump, another stud bump is stacked to form a multistage stud bump structure.

2. (original) A semiconductor device having a semiconductor chip mounted over a substrate in which an interconnect is formed, by using an adhesive layer to permit contact conduction between a stud bump of the semiconductor chip and an interconnect of a tape substrate,

wherein a stress between the semiconductor chip and the substrate is relaxed by thinning the adhesive layer.

3. (original) A semiconductor device according to Claim 2, wherein a solder resist covering the interconnect of the substrate is omitted.

4. (original) A semiconductor device having a semiconductor chip mounted over a substrate in which an interconnect is formed, by using an adhesive layer to permit contact conduction between a stud bump of the semiconductor chip and an interconnect of a tape substrate,

wherein an interconnect formation surface at the end portion of the substrate is covered with the adhesive layer.

5. (original) A semiconductor device according to Claim 4, wherein the substrate is a flexible tape substrate.

6. (original) A semiconductor device according to Claim 4, wherein the adhesive layer is a thermosetting adhesive.

7. (original) A semiconductor device having a semiconductor chip mounted over a substrate in which an interconnect is formed, by using an adhesive layer to connect a stud bump of the semiconductor chip to one end of the interconnect and an external terminal of the semiconductor device to the other end of the interconnect,

wherein a common interconnect is disposed along the

periphery of the substrate and the number of the stud bump to be connected to the common interconnect is greater than that of the external terminal to be connected to the common interconnect.

8. (original) A semiconductor device having a semiconductor chip mounted over a substrate in which an interconnect is formed, by using an adhesive layer to connect a stud bump of the semiconductor chip to one end of the interconnect and an external terminal of the semiconductor device to the other end of the interconnect,

wherein a bump electrode which will be an external terminal is formed, via a pad, at the other end of the interconnect and the pad is formed to have sufficient thickness.

9. (original) A semiconductor device according to Claim 8, wherein the pad is formed to have a substantially equal thickness to that of a base of the substrate.

Claims 10-15 (canceled).